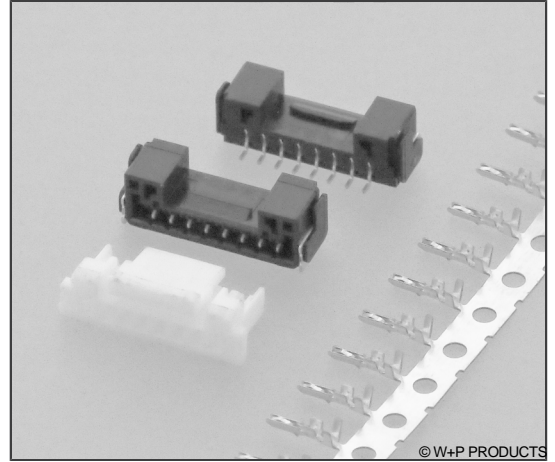


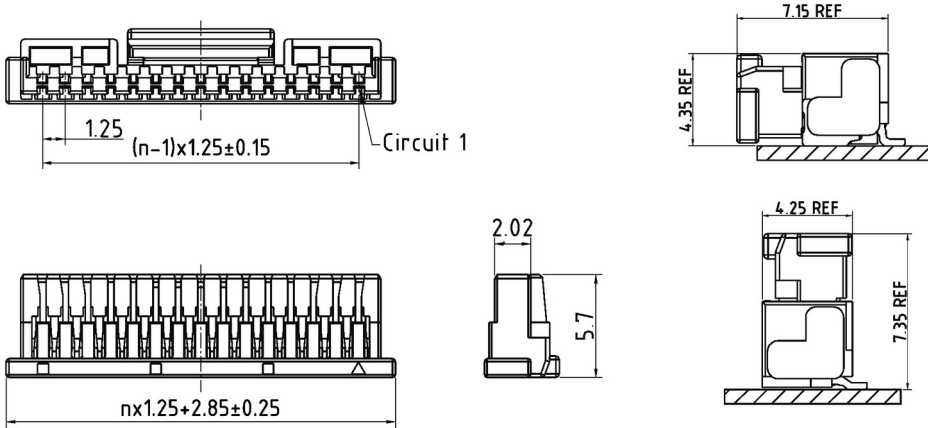
## SMT-Crimp-Rast-Stift-/Buchsenleisten RM 1,25mm – mit Verriegelung SMT Friction Lock Headers / Crimp Housings, 1.25mm Pitch – with Lock

### Technische Daten / Technical Data

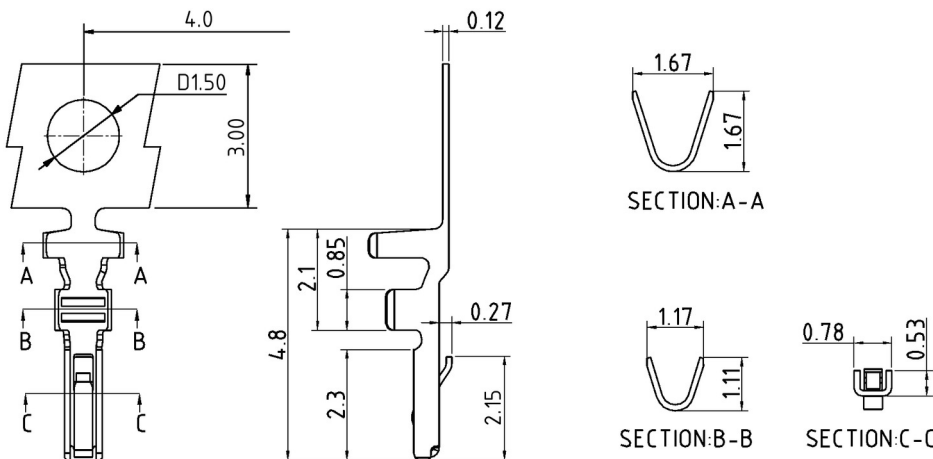
|  |   |
|--|---|
| Isolierkörper<br><i>Insulator</i>                    | Thermoplast, nach UL94 V-0, halogenfrei<br><i>Thermoplastic, rated UL94 V-0, halogen free</i> |
| Kontaktmaterial<br><i>Contact Material</i>           | Kupferlegierung<br><i>Copper alloy</i>  |
| Aderquerschnitt<br><i>Applicable wire Gauge</i>      | AWG 30 ~ 26<br><i>AWG 30 ~ 26</i>   |
| Durchgangswiderstand<br><i>Contact Resistance</i>    | < 30 mΩ<br><i>&lt; 30 mΩ</i>  |
| Isolationswiderstand<br><i>Insulation Resistance</i> | > 100 MΩ<br><i>&gt; 100 MΩ</i>  |
| Spannungsfestigkeit<br><i>Test Voltage</i>           | 500 V AC<br><i>500 V AC</i>   |
| Nennspannung<br><i>Voltage Rating</i>                | 50 V AC/DC<br><i>50 V AC/DC</i>   |
| Nennstrom<br><i>Current Rating</i>                   | 1 A AC/DC<br><i>1 A AC/DC</i>   |
| Temperaturbereich<br><i>Temperature Range</i>        | -25 °C ... +85 °C<br><i>-25 °C ... +85 °C</i>   |
| Verarbeitung<br><i>Processing</i>                    | Reflow-Lötverfahren<br><i>Reflow soldering</i>  |



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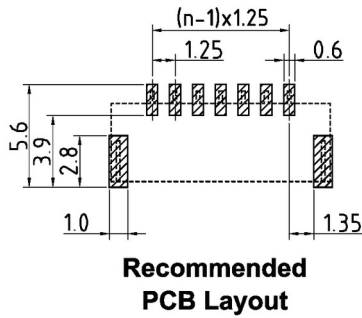
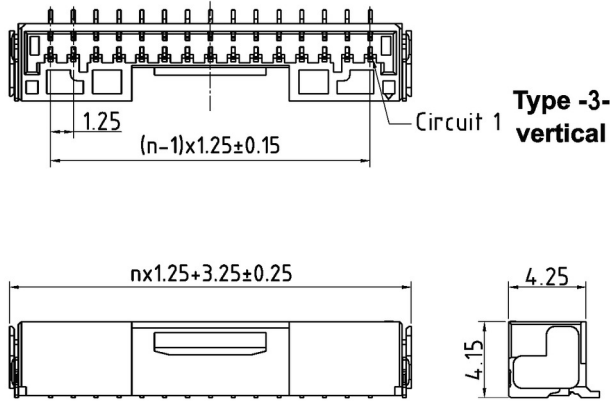
|               |                    |  |  |
|---------------|--------------------|--|--|
| <b>Series</b> | <b>Contacts*</b>   | <b>Type</b>  | <b>Colour</b>  |
| <b>5632</b>   | <b>04</b><br>02-15 | <b>1</b><br>1 Buchsengehäuse<br><i>Female Housings</i> | <b>70</b><br>70 Standard: Weiß<br><i>Standard: White</i> |



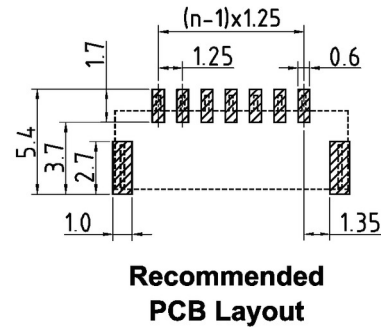
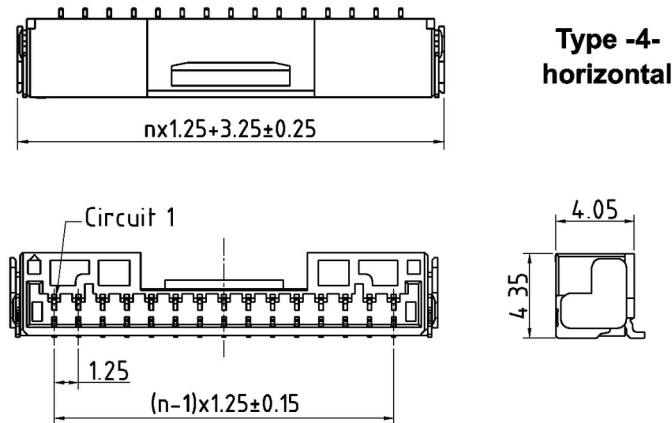
|               |                 |   |                    |
|---------------|-----------------|---|--------------------|
| <b>Series</b> | <b>Contacts</b> | <b>Type</b>   | <b>Plating</b>     |
| <b>5632</b>   | <b>01</b>       | <b>2</b><br>2 Buchsenkontakte<br><i>Female contacts</i> | <b>50</b><br>50 Sn |

# 5632

SMT-Crimp-Rast-Stift-/Buchsenleisten RM 1,25mm – mit Verriegelung  
 SMT Friction Lock Headers / Crimp Housings, 1.25mm Pitch – with Lock



| Series      | Contacts*          | Type  | Plating            | Colour   | Packaging         |
|-------------|--------------------|---|--------------------|--|-------------------|
| <b>5632</b> | <b>04</b><br>02-15 | <b>3</b><br>3 Stiffliste stehend<br>Male connector vertical | <b>50</b><br>50 Sn | <b>10</b><br>10 Standard: Schwarz<br>Standard: Black | <b>FTR</b><br>FTR |



| Series      | Contacts  | Type  | Plating   | Colour   | Packaging       |
|-------------|-----------|---|-----------|--|-----------------|
| <b>5632</b> | <b>04</b> | <b>4</b><br>4 Stiffliste liegend<br>Male connector horizontal | <b>50</b> | <b>10</b><br>10 Standard: Schwarz<br>Standard: Black | <b>TR</b><br>TR |

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
 \* This is an **order example** - please replace by your specifications.

**Lieferformen / Packaging Options:**

- FTR Tape & Reel mit Film-Pad / Tape & Reel with Film-Pad
- TR Tape & Reel ohne Pick & Place Pad / Tape & Reel w/o Pick & Place Pad

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft                    | Kennwert      |
|--------------------------------------|---------------|
| Temperatur Minimum $T_{Smin}$        | 150 °C        |
| Temperatur Maximum $T_{Smax}$        | 200 °C        |
| Dauer $T_{Smin} - T_{Smax}$          | 60 – 180s     |
| Temperatur Lötbereich $T_L$          | 217 °C        |
| Verweildauer oberhalb $T_L$          | 60 – 180s     |
| Ramp-Up Rate $T_{Smax} - T_P$        | max. 3 °C / s |
| Höchsttemperatur $T_P$               | 260±5 °C      |
| Dauer Höchsttemperatur               | 20 – 40s      |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s      |
| Dauer 25 °C – Höchsttemperatur $T_P$ | max. 8m       |

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature                      | Key Values    |
|--------------------------------------|---------------|
| Minimum Temperature $T_{Smin}$       | 150 °C        |
| Maximum Temperatur $T_{Smax}$        | 200 °C        |
| Duration $T_{Smin} - T_{Smax}$       | 60 – 180s     |
| Soldering Range Temperature $T_L$    | 217 °C        |
| Duration above $T_L$                 | 60 – 180s     |
| Ramp-Up Rate $T_{Smax} - T_P$        | max. 3 °C / s |
| Peak Temperature $T_P$               | 260±5 °C      |
| Duration Peak Temperature            | 20 – 40s      |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s      |
| Duration 25°C - Peak Temp. $T_P$     | max. 8min     |

